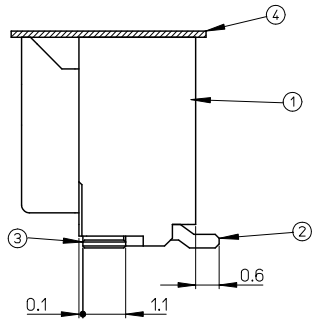
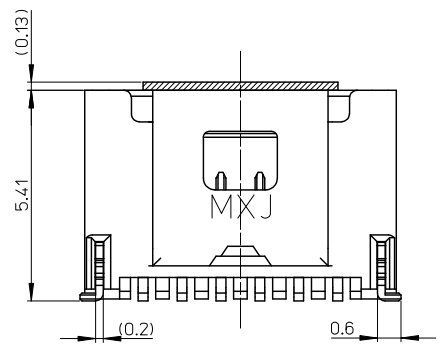


参考パターンレイアウト
RECOMMENDED PATTERN DIM. (REF)
SCALE:5:1

番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON UL94V-0, COLOR:SEE TABLE
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE



14.0	17.0	15
13.0	16.0	14
12.0	15.0	13
11.0	14.0	12
10.0	13.0	11
9.0	12.0	10
8.0	11.0	9
7.0	10.0	8
6.0	9.0	7
5.0	8.0	6
B	A	極数 CIRCUITS

※対応可能な極数は、別途お問い合わせ下さい。

- NOTES.
1. 嵌合相手: 501330-****
MATE WITH: 501330-****
 2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
 - △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
 4. 2~5極は、SD-501331-001を参照下さい。
REFER TO SD-501331-001 ABOUT 2-5CKT.
 5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

CONNECTOR SERIES No. 501331-***9

REVISED	EC NO: J2010-0339	DRAWN BY: TNAKAGAWA01	DATE: 2009/09/01	CHECKED BY: CHYKHMATSUNO	DATE: 2009/09/01	APPROVED BY: APRRCHIRATA	DATE: 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
								10 UNDER	±0.2	MM ONLY	10:1	METRIC	☉		
								10 OVER	±0.25	DRAWN BY: NYOSHIDA	DATE: 2004/07/30	TITLE	1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 6-15CKT		
								30 OVER	±0.3	CHECKED BY: MYAGI	DATE: 2004/07/30		MOLEX INCORPORATED		
								ANGULAR	±3°	APPROVED BY: MIYAZAWA	DATE: 2004/07/30	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
								DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501331-002		1 OF 2	
								THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR
501331-1597	501331-1587	501331-1577	501331-1567	15
501331-1497	501331-1487	501331-1477	501331-1467	14
501331-1397	501331-1387	501331-1377	501331-1367	13
501331-1297	501331-1287	501331-1277	501331-1267	12
501331-1197	501331-1187	501331-1177	501331-1167	11
501331-1097	501331-1087	501331-1077	501331-1067	10
501331-0997	501331-0987	501331-0977	501331-0967	9
501331-0897	501331-0887	501331-0877	501331-0867	8
501331-0797	501331-0787	501331-0777	501331-0767	7
501331-0697	501331-0687	501331-0677	501331-0667	6
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

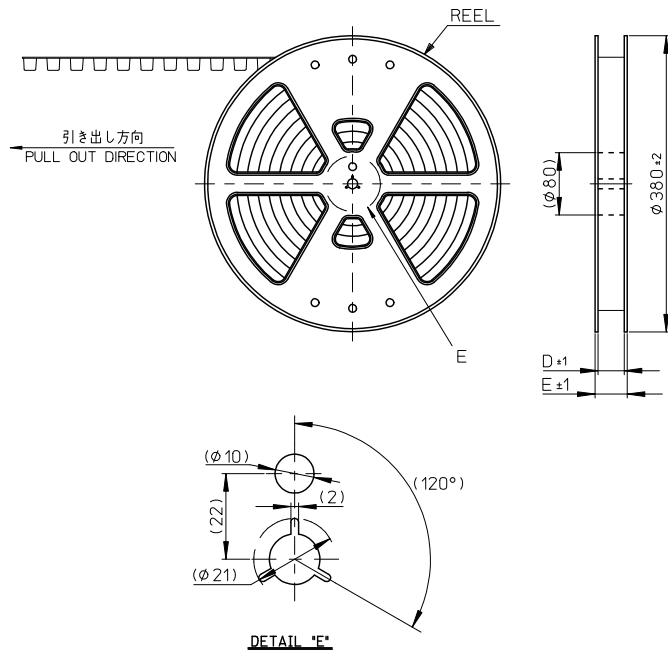
CONNECTOR SERIES No. 501331-***9

青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL	色 COLOR
501331-1547	501331-1537	501331-1527		501331-1507	15
501331-1447	501331-1437	501331-1427		501331-1407	14
501331-1347	501331-1337	501331-1327		501331-1307	13
501331-1247	501331-1237	501331-1227		501331-1207	12
501331-1147	501331-1137	501331-1127		501331-1107	11
501331-1047	501331-1037	501331-1027		501331-1007	10
501331-0947	501331-0937	501331-0927	501331-0917	501331-0907	9
501331-0847	501331-0837	501331-0827	501331-0817	501331-0807	8
501331-0747	501331-0737	501331-0727		501331-0707	7
501331-0647	501331-0637	501331-0627	501331-0617	501331-0607	6
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 501331-***9

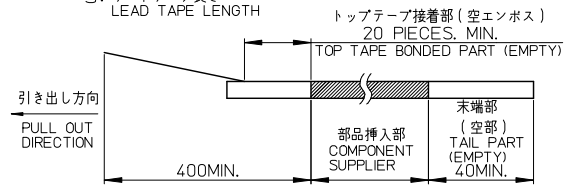
REVISED E.C. NO: J2010-0339 DRWN:TKAGAWA01 2009/09/01 CHK:KHMATSUNO 2009/09/01 APPR:HIRATA 2009/09/01 H	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2004/07/30	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 6-15CKT		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2004/07/30	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MIYAZAWA	DATE 2004/07/30	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501331-002	SHEET NO. 2 OF 2
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1

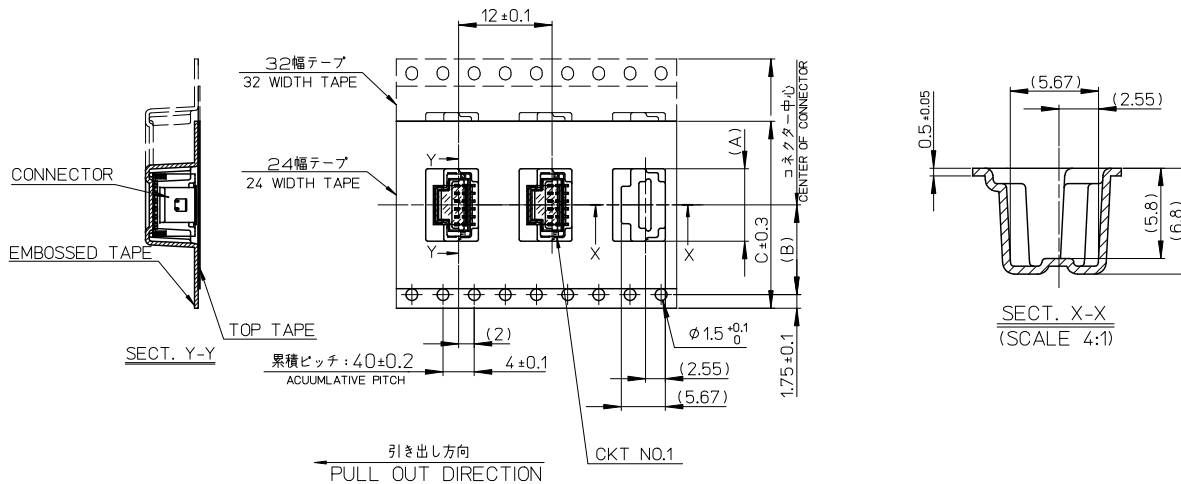


NOTES.

- 製品詳細寸法については製品単体図面を参照ください。
ABOUT DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量：1100個/リール
NUMBER OF CONNECTORS：1100PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH
トップテープ接着部（空エンボス）
20 PIECES, MIN.
TOP TAPE BONDED PART (EMPTY)
引き出し方向
PULL OUT DIRECTION
400MIN.
部品挿入部
COMPONENT
SUPPLIER
末端部
（空部）
TAIL PART
(EMPTY)
40MIN.
- 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE：POLYPROPYLENE
トップテープ：PET、PE、REF
TOP TAPE
リール：ポリスチレン（リサイクル材を含む）
REEL：POLYSTYLENE (RECYCLE MATERIAL CONTAINED)
- ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT.
- ハイバリア梱包（シリカゲル入り）対応品である。（501331-**07除く）
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501331-**07)
- 開梱後の保管条件に注意のこと。（ハイバリア品対象：PS-501331-001参照）
REFER TO PS-501331-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.



REVISED EC NO: J2010-0339 DRAWN: TAKAGAWA01 2009/09/01 CHKD: MATSUHITO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	MATERIAL NO. SEE SHEET 3	DOCUMENT NO. SD-501331-004	SHEET NO. 1 OF 3
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



37.4	33.4	32	14.2	18.3	15
				17.3	14
				16.3	13
				15.3	12
				14.3	11
				13.3	10
29.4	25.4	24	11.5	12.3	9
				11.3	8
				10.3	7
				9.3	6
E	D	C	(B)	(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501331-***9

REVISED E.C. NO: J2010-0339 DRAWN: TAKAGAWA01 2009/09/01 CHECKED BY: CHYKOHMATSUNO 2009/09/01 APPROVED BY: APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	DOCUMENT NO. SD-501331-004		
ANGULAR ±1°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 3	SHEET NO. 2 OF 3		
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1

紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
501331-1597	501331-1587	501331-1577	501331-1567	15
501331-1497	501331-1487	501331-1477	501331-1467	14
501331-1397	501331-1387	501331-1377	501331-1367	13
501331-1297	501331-1287	501331-1277	501331-1267	12
501331-1197	501331-1187	501331-1177	501331-1167	11
501331-1097	501331-1087	501331-1077	501331-1067	10
501331-0997	501331-0987	501331-0977	501331-0967	9
501331-0897	501331-0887	501331-0877	501331-0867	8
501331-0797	501331-0787	501331-0777	501331-0767	7
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EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 501331-***9

青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL	色 COLOR
501331-1547	501331-1537	501331-1527		501331-1507	15
501331-1447	501331-1437	501331-1427		501331-1407	14
501331-1347	501331-1337	501331-1327		501331-1307	13
501331-1247	501331-1237	501331-1227		501331-1207	12
501331-1147	501331-1137	501331-1127		501331-1107	11
501331-1047	501331-1037	501331-1027		501331-1007	10
501331-0947	501331-0937	501331-0927	501331-0917	501331-0907	9
501331-0847	501331-0837	501331-0827	501331-0817	501331-0807	8
501331-0747	501331-0737	501331-0727		501331-0707	7
501331-0647	501331-0637	501331-0627	501331-0617	501331-0607	6
EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 501331-***9

REVISED EC NO: J2010-0339 DRAWN: TAKAGAWA01 2009/09/01 CHKD: MATSUHITO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501331-004	SHEET NO. 3 OF 3
ANGULAR ±1°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			